

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2	"20040057214"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/17 17:31
S2	1	@ad<="20020716" and 'multichip modules' and 'IC' and 'PCB' and 'vapor chamber'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 16:10
S3	1	"6429513".PN.	USPAT; USOCR	OR	ON	2004/11/17 17:32
S4	2	@ad<="20020716" and 'multichip modules' and 'IC' and 'vapor chamber'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/19 10:43
S5	14	@ad<="20020716" and 'multichip modules' and 'IC' and 'lid' and 'dissipating'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/17 17:41
S6	5	@ad<="20020716" and 'multichip modules' and 'IC' and 'hollow' same 'heat'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/17 17:41
S7	31	@ad<="20020716" and 'multichip modules' and 'hollow' same 'heat'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/17 17:44
S8	1	"6429513".PN.	USPAT; USOCR	OR	ON	2004/11/17 17:48
S9	1	"6212074".PN.	USPAT; USOCR	OR	ON	2004/11/17 17:48
S10	1	"6166908".PN.	USPAT; USOCR	OR	ON	2004/11/17 17:49
S11	1	"6091603".PN.	USPAT; USOCR	OR	ON	2004/11/17 17:50
S12	81	@ad<="20020716" and 'heat sink' same 'vapor chamber'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/17 17:50
S13	1	"6429513".PN.	USPAT; USOCR	OR	ON	2004/11/18 07:40
S14	1	"5880524".PN.	USPAT; USOCR	OR	ON	2004/11/18 07:40
S15	1	"5915463".PN.	USPAT; USOCR	OR	ON	2004/11/18 07:40

S16	6	@ad<="20020716" and 'MCM' and 'vapor chamber' and 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/19 10:56
S17	81	@ad<="20020716" and 'vapor chamber' same 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 10:24
S18	1	"6237223".PN.	USPAT; USOCR	OR	ON	2004/11/18 08:11
S19	1	"6062302".PN.	USPAT; USOCR	OR	ON	2004/11/18 08:12
S20	1	"5864466".PN.	USPAT; USOCR	OR	ON	2004/11/18 08:12
S21	1	"5704416".PN.	USPAT; USOCR	OR	ON	2004/11/18 08:12
S22	1	"5647430".PN.	USPAT; USOCR	OR	ON	2004/11/18 08:13
S23	1	"6269865".PN.	USPAT; USOCR	OR	ON	2004/11/18 08:14
S24	1	"6269865".PN.	USPAT; USOCR	OR	ON	2004/11/18 08:14
S25	1	"6164368".PN.	USPAT; USOCR	OR	ON	2004/11/18 08:14
S26	1339	@ad<="20020716" and (438/122-123).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 09:00
S27	647	@ad<="20020716" and (438/125).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 09:01
S28	115	@ad<="20020716" and (438/55).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 09:01
S29	1496	@ad<="20020716" and (257/706-707).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 09:01
S30	1483	@ad<="20020716" and (257/704-705).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/14 16:40

S31	719	@ad<="20020716" and (257/675). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 09:02
S32	874	@ad<="20020716" and (257/717). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 10:12
S33	1041	@ad<="20020716" and (257/721-722).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 09:02
S34	1922	@ad<="20020716" and (361/704). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 09:02
S35	556	@ad<="20020716" and (361/709). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 09:03
S36	130	@ad<="20020716" and (361/711). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 09:03
S37	336	@ad<="20020716" and (361/717). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 09:03
S38	929	@ad<="20020716" and (361/719). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 09:04
S39	797	@ad<="20020716" and (361/690-691).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 09:04
S40	1055	@ad<="20020716" and (165/104. 33).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 09:04
S41	848	@ad<="20020716" and (165/104. 21).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 09:04

S42	1	"5751062".PN.	USPAT; USOCR	OR	ON	2004/11/18 09:35
S43	1	"5930115".PN.	USPAT; USOCR	OR	ON	2004/11/18 10:06
S44	1	"5880930".PN.	USPAT; USOCR	OR	ON	2004/11/18 10:06
S45	1	"5625227".PN.	USPAT; USOCR	OR	ON	2004/11/18 10:06
S46	1	"5345107".PN.	USPAT; USOCR	OR	ON	2004/11/18 10:06
S47	1	"4612978".PN.	USPAT; USOCR	OR	ON	2004/11/18 10:09
S48	1	"5179500".PN.	USPAT; USOCR	OR	ON	2004/11/18 10:09
S49	1	"5325265".PN.	USPAT; USOCR	OR	ON	2004/11/18 10:09
S50	1	"5704416".PN.	USPAT; USOCR	OR	ON	2004/11/18 10:09
S51	1	"5880524".PN.	USPAT; USOCR	OR	ON	2004/11/18 10:10
S52	1	"5915463".PN.	USPAT; USOCR	OR	ON	2004/11/18 10:10
S53	1	"6085831".PN.	USPAT; USOCR	OR	ON	2004/11/18 10:10
S54	1	"6091603".PN.	USPAT; USOCR	OR	ON	2004/11/18 10:10
S55	1	"5880524".PN.	USPAT; USOCR	OR	ON	2004/11/18 10:11
S56	33	@ad<="20020716" and (257/717). ccls. and 'chamber'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/14 16:42
S57	43	@ad<="20020716" and (257/717). ccls. and 'pipe'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 10:13
S58	67	@ad<="20020716" and 'chamber' same 'heat spreader'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 10:24
S59	206	@ad<="20020716" and 'pipe' same 'heat spreader'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 10:25

S60	9	@ad<="20020716" and 'heatpipe' same 'heat spreader'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 10:25
S61	190	@ad<="20020716" and 'heat pipe' same 'heat spreader'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/19 10:52
S62	1	"5325265".PN.	USPAT; USOCR	OR	ON	2004/11/19 09:36
S63	1	"5704416".PN.	USPAT; USOCR	OR	ON	2004/11/19 09:36
S64	0	@ad<="20020716" and 'multichip modules' and 'IC' and 'stiffener' with 'polermer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/19 10:47
S65	42	@ad<="20020716" and 'PGA' same 'substrate' with 'polymer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/19 10:47
S66	6	@ad<="20020716" and 'multichip modules' and 'IC' and 'stiffener' with 'polymer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/19 10:47
S67	0	@ad<="20020716" and 'heat pipe' same 'heat spreader' and 'substrate' with 'polymer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/19 10:52
S68	50	@ad<="20020716" and 'heat pipe' and 'substrate' with 'polymer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/19 10:53
S69	112	@ad<="20020716" and 'MCM' and 'heat sink' and 'substrate' with 'polymer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/19 11:06
S70	3	@ad<="20020716" and 'MCM' same 'heat sink' same 'substrate' with 'polymer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/19 10:56
S71	0	@ad<="20020716" and 'MCM' and 'package substrate' with 'polymer' with 'ceramic'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/19 11:06

S72	6	@ad<="20020716" and 'MCM' and 'package substrate' with 'polymer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/15 09:48
S73	3	@ad<="20020716" and 'package substrate' with 'polymer' with 'ceramic'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/14 16:09
S74	6	Alcoe-David.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/14 15:31
S75	33	'Alcoe David J'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 16:00
S76	22	'Alcoe David J' and 'CTE'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/14 15:32
S77	1	"6429513".PN.	USPAT; USOCR	OR	ON	2005/03/14 15:35
S78	419	@ad<="20020716" and 'package' and 'chamber' and ('coefficient of thermal expansion' or 'CTE')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/14 16:10
S79	5	@ad<="20020716" and 'package' and 'vapor chamber' and ('coefficient of thermal expansion' or 'CTE')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/14 17:17
S80	15	@ad<="20020716" and 'vapor chamber' and ('coefficient of thermal expansion' or 'CTE')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/14 17:18
S81	7	@ad<="20020716" and 'lidded package' and ('coefficient of thermal expansion' or 'CTE')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/14 17:19
S82	32	@ad<="20020716" and ('multichip modules' or 'MCM') and 'substrate' with 'ceramic' with 'fiberglass'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/15 07:19

S83	3	@ad<="20020716" and ('multichip modules' or 'MCM') and 'heat sink' and 'substrate' with 'ceramic' with 'fiberglass'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/15 07:19
S84	1	"6392890".PN.	USPAT; USOCR	OR	ON	2005/03/15 07:32
S85	1	"6292369".PN.	USPAT; USOCR	OR	ON	2005/03/15 07:32
S86	1	"5387815".PN.	USPAT; USOCR	OR	ON	2005/03/15 07:32
S87	1	"6288900".PN.	USPAT; USOCR	OR	ON	2005/03/15 07:37
S88	1	"6264882".PN.	USPAT; USOCR	OR	ON	2005/03/15 07:38
S89	1	"4425195".PN.	USPAT; USOCR	OR	ON	2005/03/15 07:38
S90	1	"6114048".PN.	USPAT; USOCR	OR	ON	2005/03/15 07:38
S91	1	"6097602".PN.	USPAT; USOCR	OR	ON	2005/03/15 07:39
S92	1	"5945217".PN.	USPAT; USOCR	OR	ON	2005/03/15 07:39
S93	14	@ad<="20020716" and 'MCM' and 'package substrate' same 'lid'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/15 09:48
S94	172	@ad<="20020716" and 'package substrate' same 'lid'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/15 09:48
S95	7	'hong xie'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 16:03
S97	142	'xie' and 'intel'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 16:04
S98	16	@ad<="20020716" and 'Heat pipe lid'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 16:17
S99	1	"5751062".PN.	USPAT; USOCR	OR	ON	2005/06/23 16:10
S100	1	"5625227".PN.	USPAT; USOCR	OR	ON	2005/06/23 16:11

S10 1	1	"5365400".PN.	USPAT; USOCR	OR	ON	2005/06/23 16:11
S10 2	1	"5349237".PN.	USPAT; USOCR	OR	ON	2005/06/23 16:11
S10 3	1	"5345107".PN.	USPAT; USOCR	OR	ON	2005/06/23 16:11
S10 4	1	"5329993".PN.	USPAT; USOCR	OR	ON	2005/06/23 16:12
S10 5	1	"5283715".PN.	USPAT; USOCR	OR	ON	2005/06/23 16:12
S10 6	1	"20030128521".PN.	US-PGPUB	OR	ON	2005/06/23 16:12
S10 7	1	"20020132896".PN.	US-PGPUB	OR	ON	2005/06/23 16:13
S10 8	1	"5403783".PN.	USPAT; USOCR	OR	ON	2005/06/23 16:13
S10 9	1	"5355942".PN.	USPAT; USOCR	OR	ON	2005/06/23 16:14
S11 0	1	"5323292".PN.	USPAT; USOCR	OR	ON	2005/06/23 16:14
S11 1	1	"4880052".PN.	USPAT; USOCR	OR	ON	2005/06/23 16:15
S11 5	3	@ad<="20020716" and 'Heat pipe' and 'sub-chamber' and 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 16:20
S11 6	6	@ad<="20020716" and 'Heat pipe' and 'sub-chamber'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 16:21
S11 8	260	@ad<="20020716" and 'Heat pipe' same 'support' and 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 16:22
S11 9	0	@ad<="20020716" and 'Heat pipe' same 'chamber' and 'wiring board' with 'ceramic'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/27 12:07
S12 0	12	@ad<="20020716" and 'Heat pipe' same 'chamber' and 'board' with 'ceramic'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/27 12:41
S12 1	168	@ad<="20020716" and 'PCB' with 'ceramic' and 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/27 12:42



S12 2	0	@ad<="20020716" and 'PCB' with 'ceramic' with 'polymer' and 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/27 12:41
S12 3	39	@ad<="20020716" and 'PCB' with 'ceramic' same 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/27 12:44
S12 4	3	@ad<="20020716" and 'vapor chamber' and 'PCB' with 'ceramic' and 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/27 12:52
S12 5	176	@ad<="20020716" and 'vapor chamber' and 'heat pipe'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/27 12:52